



APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate |
|--|---|
| <p>TO:</p> <p>Part No.:</p> <p>Customer's Part No.:</p> | <p>Please return this copy as a certification of your approval</p> <p>Checked & Approved by:</p> <p>Date:</p> |

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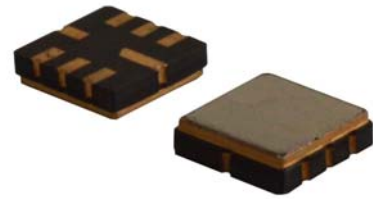


| | | |
|----------|---|-----------|
| Part No. | : | SF3237 |
| Pages | : | 6 |
| Date | : | 2014/4/10 |
| Revision | : | 1.0 |

| | |
|---------------------|----|
| Prepared by: | 梁浩 |
| Checked by: | |
| Approved by: | |

Application

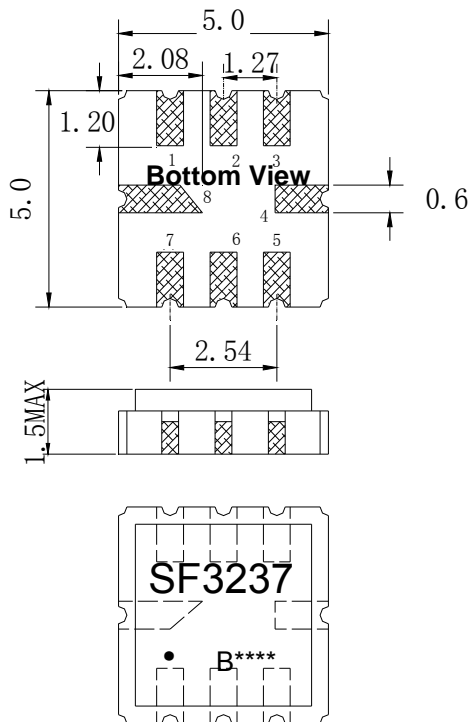
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 2 MHz



Features

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 5.00x5.00x1.50mm³
- Package Code QCC8C
- **Electrostatic Sensitive Device(ESD)**

Package Dimensions (Unit: mm)



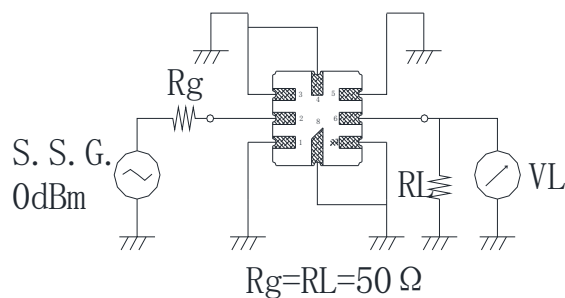
Pin Configuration

| Pin No. | Description |
|-------------|-------------|
| 2 | Input |
| 6 | Output |
| 1,3,4,5,7,8 | Ground |

Marking Description

| | |
|--------------|------------------------|
| S | Trademark |
| F | SAW Filter |
| 3237 | Part Number |
| ● | Pin 1 |
| B**** | Year Code & Serial No. |

Test Circuit(Bottom View)



Performance**Maximum Rating**

| Item | | Value | Unit |
|-----------------------|------------------|------------|------|
| DC Voltage | V _{DC} | 3 | V |
| Operation Temperature | T | -55 ~ +85 | °C |
| Storage Temperature | T _{stg} | -55 ~ +125 | °C |
| RF Power Dissipation | P | 10 | dBm |

Electronic Characteristics

Test Temperature: 25°C ± 2°C

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

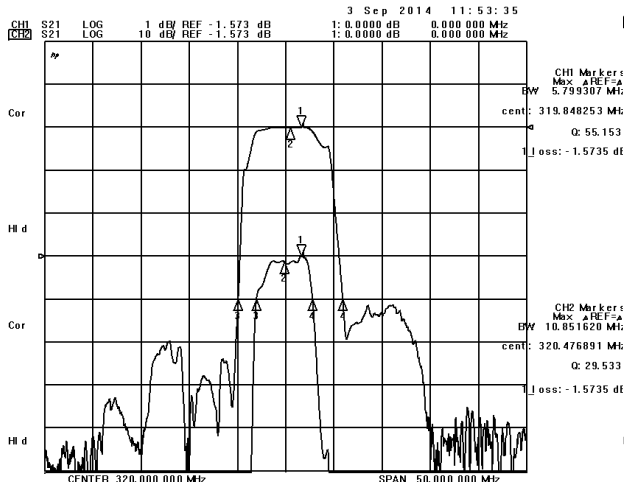
| Item | | Minimum | Typical | Maximum | Unit |
|------------------------|-------------------|---------|---------|---------|------|
| Center Frequency | f _c | 319.8 | 320.0 | 320.2 | MHz |
| Insertion Loss(min) | IL | | 1.6 | 5.0 | dB |
| Amplitude Ripple (p-p) | Δα | | 0.3 | 1.0 | dB |
| 1 dB Bandwidth | BW _{1dB} | 4.0 | 5.8 | | MHz |
| | 220.00-280.00MHz | 55.0 | 65.0 | | dB |
| | 280.00-314.00MHz | 40.0 | 50.0 | | dB |
| | 326.00-360.00MHz | 40.0 | 42.0 | | dB |
| | 360.00-420.00MHz | 55.0 | 65.0 | | dB |
| Input VSWR | 317.50-322.50MHz | | 1.5:1 | 2.0:1 | / |
| Output VSWR | 317.50-322.50MHz | | 1.5:1 | 2.0:1 | / |

The following is Electronic Characteristics Consistency, What Among the same batch Or the other batch.

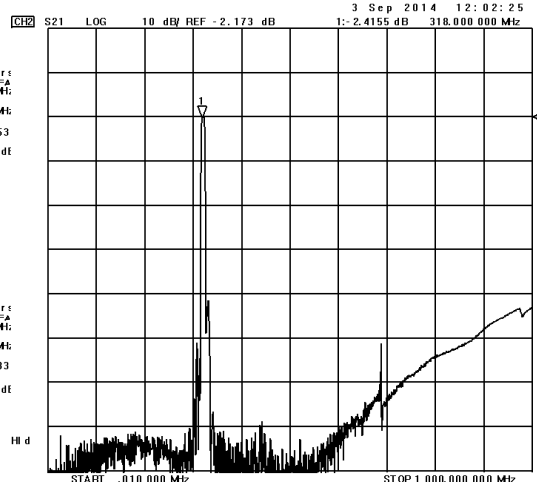
| | | | | | |
|---|--|--|--|-------|-----|
| Amplitude Consistency(Fc) | | | | ±0.5 | dB |
| Amplitude Second Inconsistency 319.00-321.00 MHz | | | | ±0.25 | dB |
| Phase Consistency(Fc) | | | | ±8 | deg |
| Phase Second Inconsistency 319.00-321.00 MHz | | | | ±2.5 | deg |
| Group Delay Consistency(Fc) | | | | 1 | ns |

Frequency Characteristics

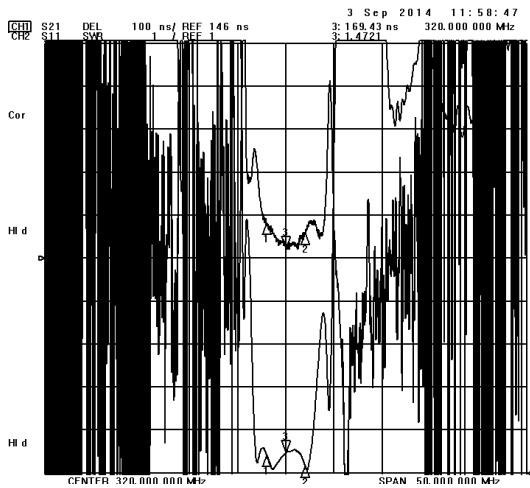
Frequency Response



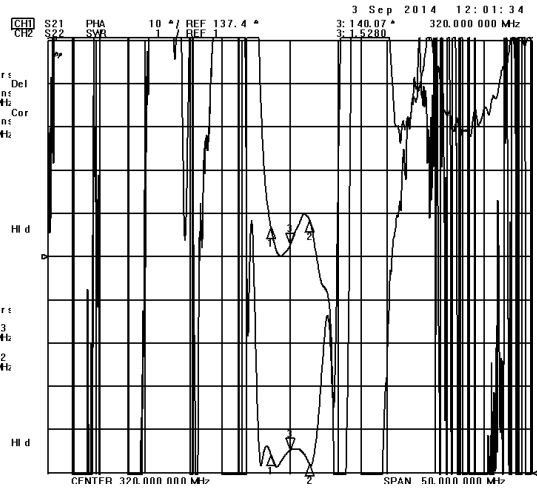
Frequency Response (wideband)



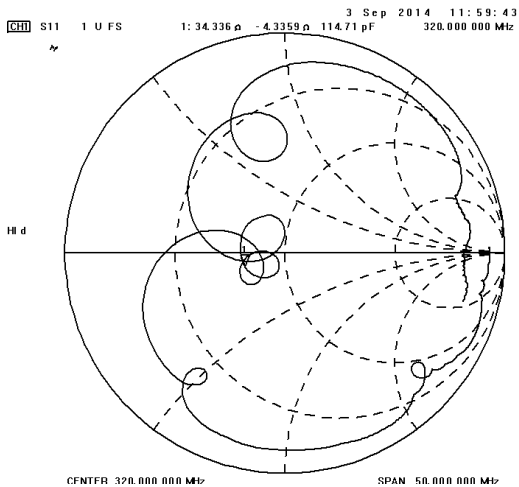
Delay Ripple & S11 VSWR



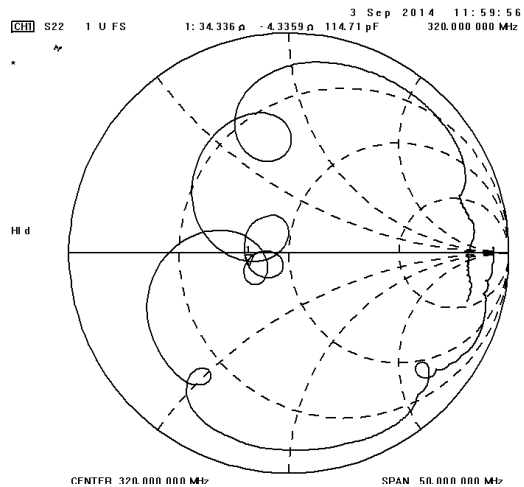
Phase Linearity & S22 VSWR



S11 Smith Chart



S22 Smith Chart



Packing Information

Carrier Tape



* B0: 5.35 for QCC8C; 4.15 for DCC6/QCC8B; 3.35 for DCC6C/QCC8D

Reel Dimensions



Outer Packing

| Type | Quantity | Dimension | Description | Weight |
|--------------|----------|-------------|-------------------------------------|--------|
| Internal box | 1000 | 190×188×42 | carton box 2 reel / internal box | 0.18 |
| External box | 10000 | 235×205×210 | 5 boxes / external box | 1.80 |

Unit: mm

Unit: kg

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.